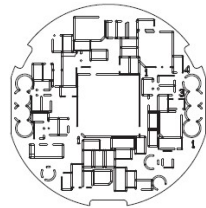
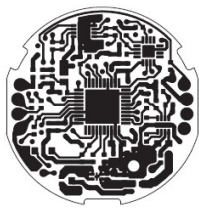
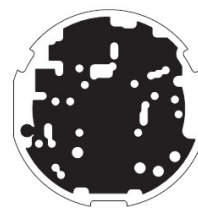
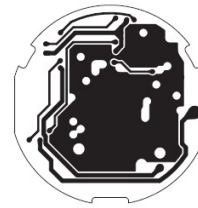
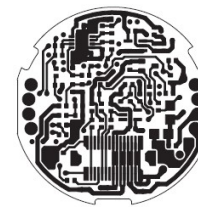


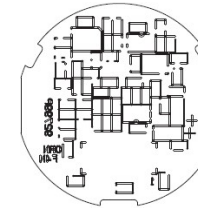
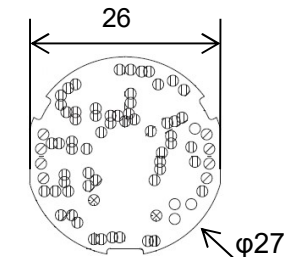
RKP-92799P

SILK PRINT FOR
PARTS SIDE

PARTS SIDE

INNER LAYER
(2 LAYER)INNER LAYER
(3 LAYER)

SOLDERING SIDE

SILK PRINT FOR
SOLDERING SIDE

THROUGH HOLE

MARK	DIAGRAM	HOLE	MEMO
⊕	φ 0.3	TH	
○	φ 0.5	TH	
⊗	φ 0.9	TH	
⊗	φ 0.65	NTH	

All drawings are view of L1 side
SCALE 1:1

SPECIFICATION FOR PCB

- PCB No. : RKP-92799P
- Material : Glass epoxy
- Thickness : 1.2mm
- Layer number : 4
- Thickness copper film : 35um
- Minimum conductor width : 0.2mm
- CTI : 100 above

PARTS LIST

Mark of drawing	Kind of parts	Rating / Model of parts	Remarks
IC1	IC(CPU)	R5F51113AGNF [RENESAS]	
IC2	IC(LDO)	LTC3035EDDB [AD]	
IC3	IC(OPAMP)	OPA333AIDCKR [TI]	
IC4,IC5	IC(OPAMP)	LTC2055HDD [AD]	
IC6	IC(Digital potentiometer)	TPL0202-10MRTER [TI]	
IC7	IC(LDO)	S-1335A28-A4T2 [ABLIC]	
IC8,	IC(Buffer)	SN74LVC1G17DCK [TI]	
Q1	Nch MOS FET	RU1C002UN [ROHM]	
D1,	Schottky Barrier Diode	RB168VAM-30 [ROHM]	
D2,	Schottky Barrier Diode	1PS76SB40 [NXP]	
R1-R15,R18,R19,R2 1-R49,R51-R62	Chip fixed resistor or Chip jumper	1 ohm - 1M ohm / 1%, 0.063W or 50m ohm max,1A (1005)	
C1-C13,C17-C32,C3 5-C36,C40-C49	Chip multilayer capacitor	Total capacitance 36.5uFmax	
C44,C45	Chip Tantalum Capacitor	Total capacitance 12.3uFmax	

All components may be replaced with equivalent components or may not be mounted.

注 記 NOTES		改版担当者 REV. BY	改版日 REVISED	名称 NAME
改版回数 REV.	0	総頁数 PAGES	1	DIGITAL PCB FOR MODEL IRF
承認 APPROVED	検 討 CHECKED	製 図 DRAWN	作成日 DATE	図 番 DWG. NO.
北村正英	小野圭	神沢朋和	2021.4.7	E 3 - 6 9 9 1 - 6 1 9 6 - 5 0 - 0 1 K

RIKEN KEIKI

理研計器株式会社

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SCHEMATIC

